



Product Change Notification - LIAL-22CVKD642

Date:

04 Apr 2018

Product Category:

Memory; Simple and Complex Programmable Logic

Affected CPNs:**Notification subject:**

CCB 3315, 3315.001 Initial Notice: Qualification of MMT as a new assembly site for selected Atmel products in 19.7K, 34K, and 35.5K wafer technology available in 44L and 28L PLCC packages.

Notification text:**PCN Status:**

Initial notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found on the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of MMT as a new assembly site for selected Atmel products in 19.7K, 34K, and 35.5K wafer technology available in 44L and 28L PLCC packages.

Pre Change:

Assembled in ANAP using CRM-1076E die attach and A194 lead frame material or assembled in LPI using CRM-1033BF die attach and C151 lead frame material.

Post Change:

Assembled in MMT using 3280 die attach and C151 lead frame material.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Lingsen Precision Industires, LTD. (LPI)	Microchip Technology Thailand (Branch) (MMT)
Wire material	Au	Au	Au
Die attach material	CRM-1076E	CRM-1033BF	3280
Molding compound material	G600	G600	G600
Lead frame material	A194	C151	C151

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MMT as a new assembly site



Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

April 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	April 2018				
Workweek	14	15	16	17	18
Initial PCN Issue Date	X				
Qual Report Availability				X	
Final PCN Issue Date				X	

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

April 04, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_LIAL-22CVKD642_QUAL_PLAN.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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QUALIFICATION PLAN SUMMARY

PCN #: LIAL-22CVKD642

Date

March 08, 2018

Qualification of MMT as a new assembly site for selected Atmel products in 19.7K, 34K, and 35.5K wafer technology available in 44L PLCC packages. The selected products available in 28L PLCC packages will be qualify by similarity (QBS).

Purpose: Qualification of MMT as a new assembly site for selected Atmel products in 19.7K, 34K, and 35.5K wafer technology available in 44L PLCC packages. The selected products available in 28L PLCC packages will be qualify by similarity (QBS).

CCB No.: 3315 and 3315.001

		Qualification Report
<u>Misc.</u>	Assembly site	MMT
	BD Number	BDM-001712 rev A
	MP Code (MPC)	340357T2XC01
	Part Number (CPN)	AT27BV1024-90JU
<u>Lead-Frame</u>	Paddle size	230x230
	Material	CDA151
	Surface	Ag Spot Plated
	Treatment	None
	Process	Stamped
	Lead-lock	No
	Part Number	10104409
	Lead Plating	Matte Tin
<u>Bond Wire</u>	Material	Au
<u>Die Attach</u>	Part Number	3280
	Conductive	Yes
<u>Die Coat</u>	Part number	Q1-4939
<u>MC</u>	Part Number	G600V
<u>PKG</u>	PKG Type	PLCC
	Pin/Ball Count	44
<u>Die</u>	Die Thickness	15 mils
	Die Size	139.0x146.0 mils
	Fab Process (site)	34K/MCSO

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail/Accept Qty	Est. Dur. Days	Test Site	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	15	0 fails after TC	5	MMT/MTAI	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	15	0	5	MMT/MTAI	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		MMT	Required for any reduction in wire bond thickness.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	MTAI	
HTSL (High Temp Storage Life)	+175 C for 504 hours. Electrical test pre and post stress at +25°C and hot temp.85°C. 1 lot to be tested at 125C	45	5	1	50	0	25	MTAI	
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jeduc-STD-020D for package type; Electrical test pre and post stress at +25°C. MSL1 @ 245°C	231	15	3	738	0	15	MTAI	Spares should be properly identified. .
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp. 1 lot to be tested at 85C	77	5	3	246	0	10	MTAI	Spares should be properly identified.
Unbiased HAST	+130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	MTAI	Spares should be properly identified.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. 1 lot to be tested at 85C	77	5	3	246	0	15	MTAI	Spares should be properly identified.

LIAL-22CVK 3315.001 | 34K

and 35.5K wafer technology available in 44L and 28L PLCC packages.

Affected Catalog Part Numbers(CPN)

AT27BV1024-90JU
AT27BV1024-90JU-T
AT27C1024-45JU
AT27C1024-45JU-T
AT27C1024-70JU
AT27C1024-70JU-T
AT27C2048-55JU
AT27C2048-55JU-T
AT27C2048-90JU
AT27C2048-90JU-T
AT27C4096-55JU
AT27C4096-55JU-T
AT27C4096-90JU
AT27C4096-90JU-T
AT27C4096-90JUT-441
ATF1500A-10JU
ATF1500AL-20JU
ATF1502AS-10JU44
ATF1502AS-10JU44-113
ATF1502AS-7JX44
ATF1502AS-7JX44-T
ATF1502ASL-25JU44
ATF1502ASV-15JU44
ATF1504AS-10JU44
ATF1504AS-10JU44-T
ATF1504AS-7JX44
ATF1504ASL-25JU44
ATF1504ASV-15JU44
ATF1504ASV-15JU44-T
ATF1504ASVL-20JU44
ATF1504ASVL-20JU44-T
ATF22LV10C-10JU
ATF22LV10CQZ-30JU
ATF22V10C-10JU
ATF22V10C-15JU
ATF22V10C-5JX
ATF22V10C-7JU
ATF22V10C-7JU-T
ATF22V10CQ-15JU
ATF22V10CQZ-20JU
ATF22V10CQZ-20JU-T
ATF2500C-15JU

ATF750C-10JU
ATF750C-7JX
ATF750CL-15JU
ATF750LVC-15JU

